

AT1005 Series

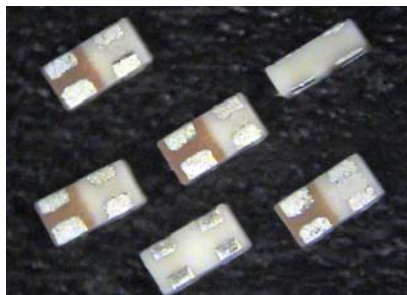
Multilayer Chip Antenna

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖ RoHS compliant

Applications

- ❖ Bluetooth/Wireless LAN/Home RF
- ❖ ISM band 2.4GHz applications



Specifications

Part Number	Frequency Range (MHz)	Peak Gain (dBi typ.)	Average Gain (dBi typ.)	VSWR	Impedance
AT1005-A2R4LGA	2400~2480	1.0 (XZ-Total)	-1.5 (XZ-Total)	3.0 max.	50 Ω

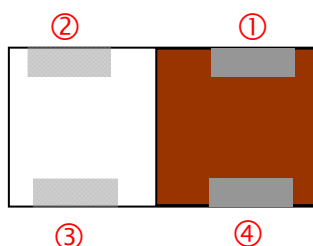
Q'ty/Reel (pcs) : 10,000 pcs
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : -40 ~ +85 °C
 Storage Period : 12 months max.
 Power Capacity : 2W max.

Part Number

AT 1005 - A 2R4 LGA □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	AT : Antenna	② Dimensions (L x W)	1.0x 0.5 mm
③ Material Code	A	④ Frequency Range	2R4=2450MHz
⑤ Specification Code	LGA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

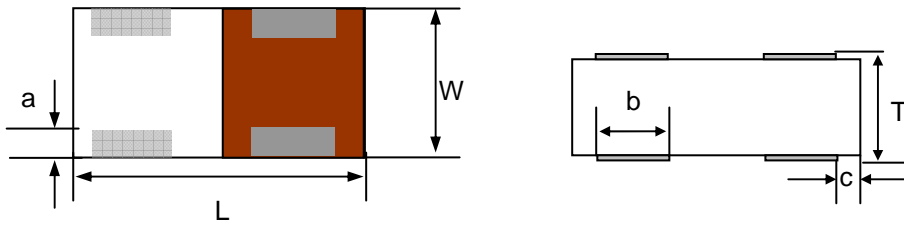
Terminal Configuration



No.	Terminal Name	No.	Terminal Name
①	Feed	③	GND
②	GND	④	Feed

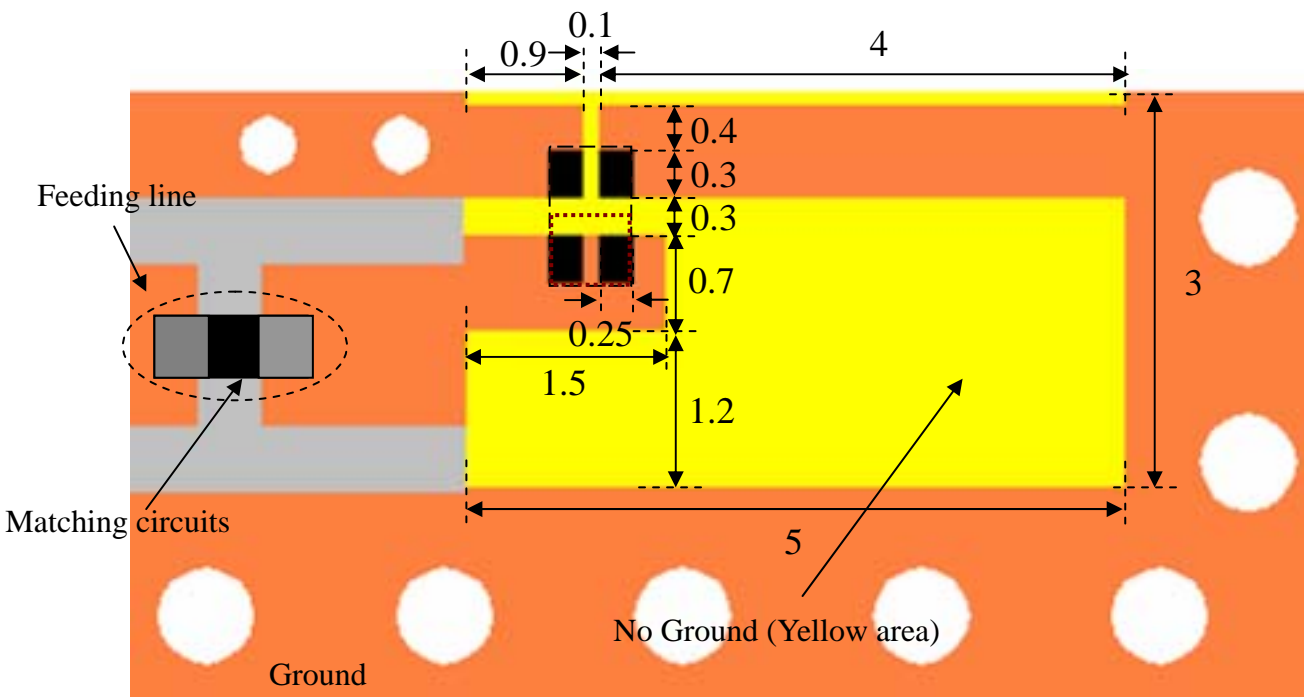
Dimensions and Recommended PC Board Pattern

Unit : mm



Mark	L	W	T	a	b	c
Dimensions	1.0 ± 0.1	0.5 ± 0.1	0.37 max	0.15 +0.1/-0.05	0.25 +0.1/-0.05	0.08 +0.1/-0.05

❖ Without Matching Circuits (Unit in mm)

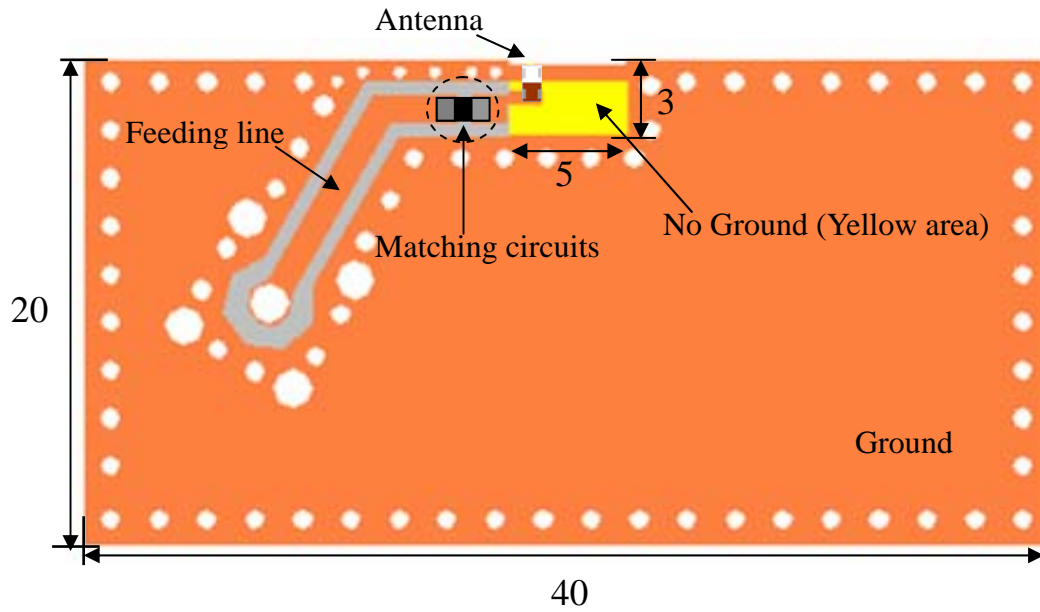


- Solder Resist
- Land

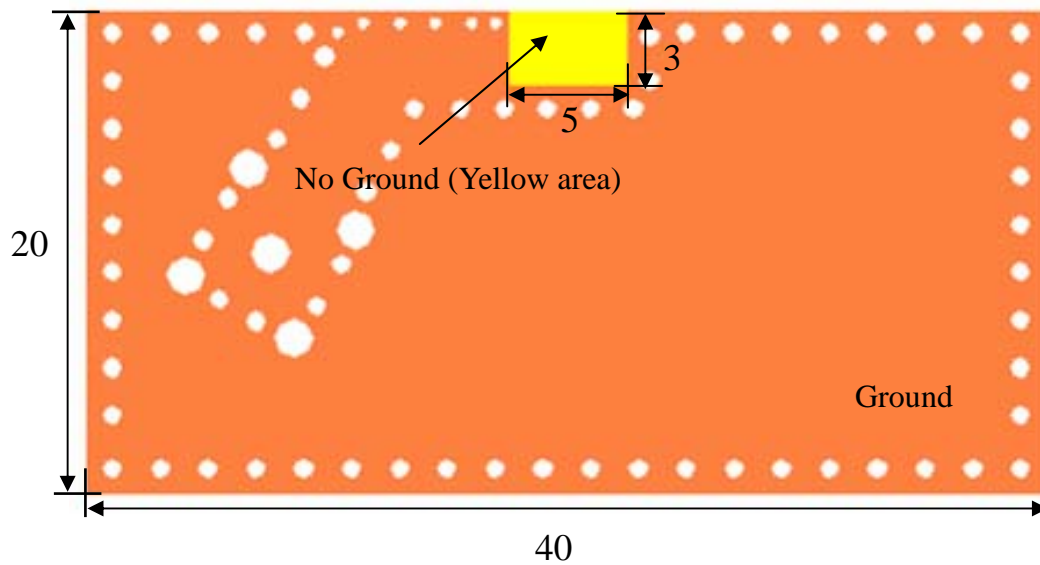
*Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

Typical Electrical Characteristics (T=25°C)

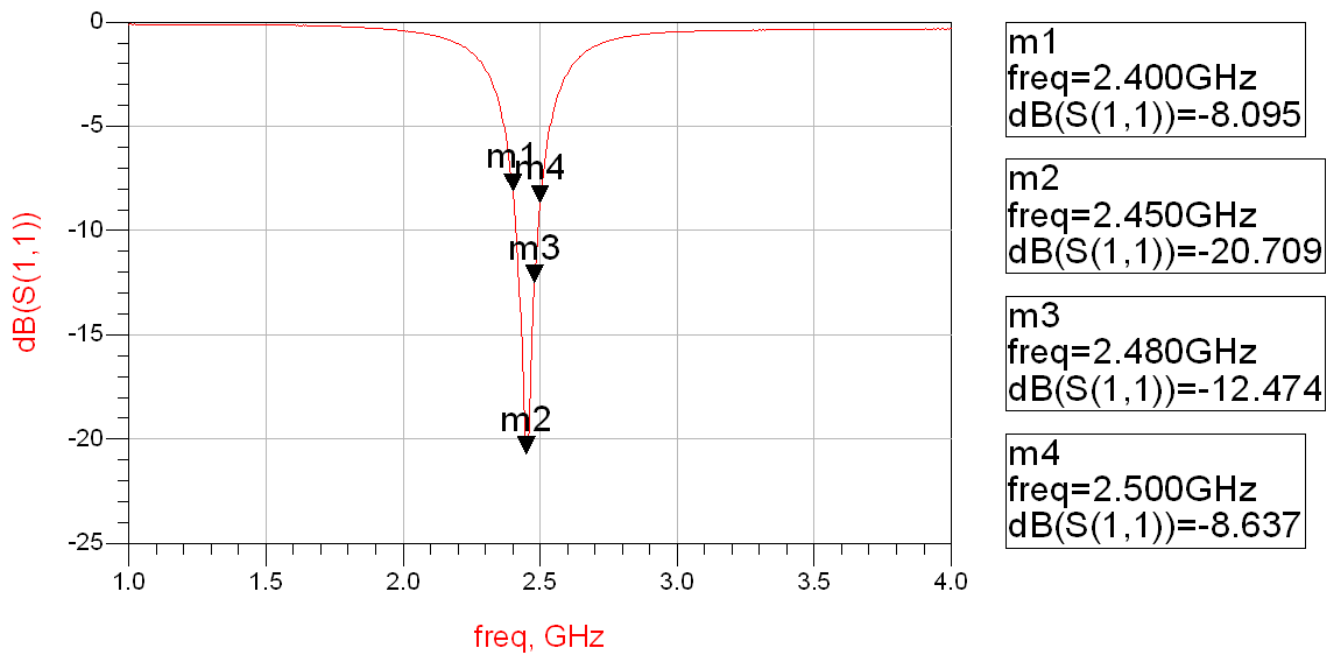
❖ Test Board-Top View (Unit in mm)



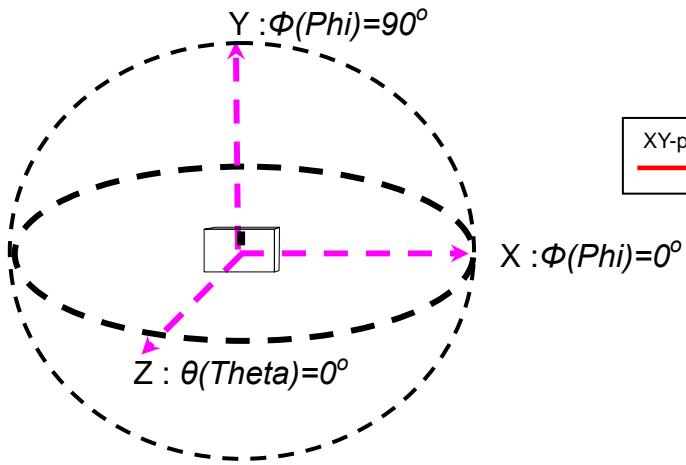
❖ Test Board-Bottom View (Unit in mm)



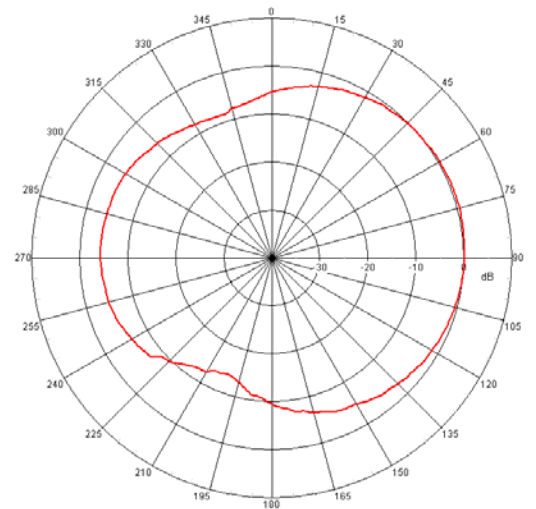
❖ Return Loss / Without Matching Circuits



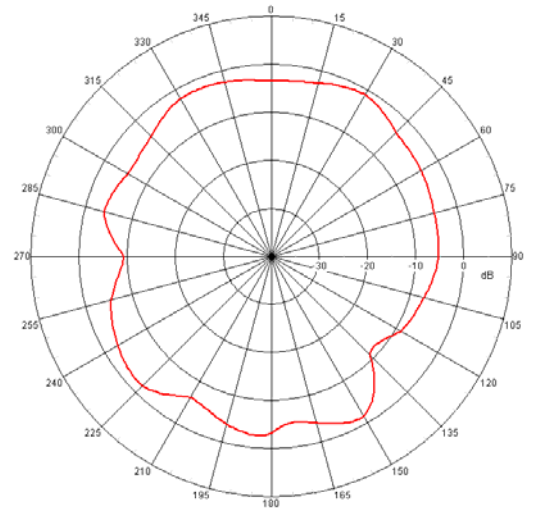
❖ Radiation Patterns (Antenna Efficiency: 2400 / 2440 / 2480MHz: 49 / 58 / 51%)



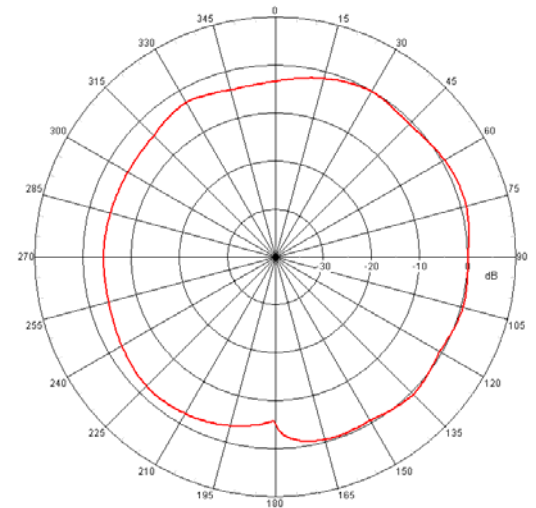
XY-plane @2440MHz
— Total



XZ-plane @2440MHz
— Total

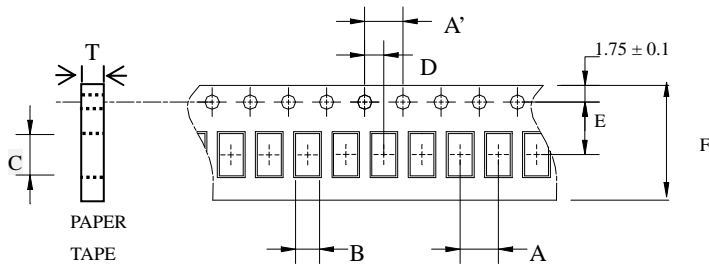


YZ-plane @2440MHz
— Total



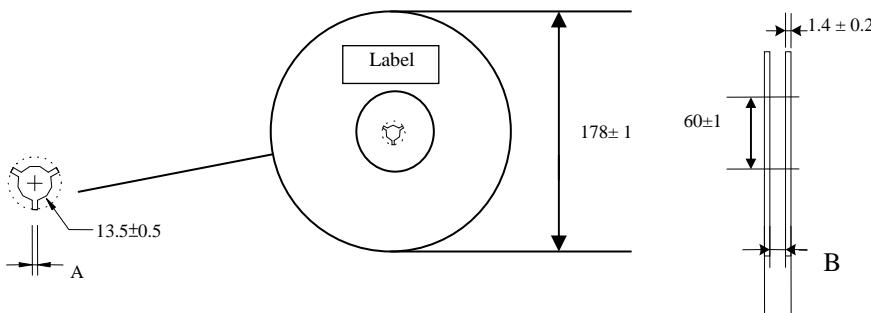
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1005	2.0±	4.0±	0.62±	1.12±	2.0±	3.5±	8.0±	0.43±	10,000pcs	Paper
	0.05	0.1	0.03	0.03	0.05	0.05	0.1	0.03		

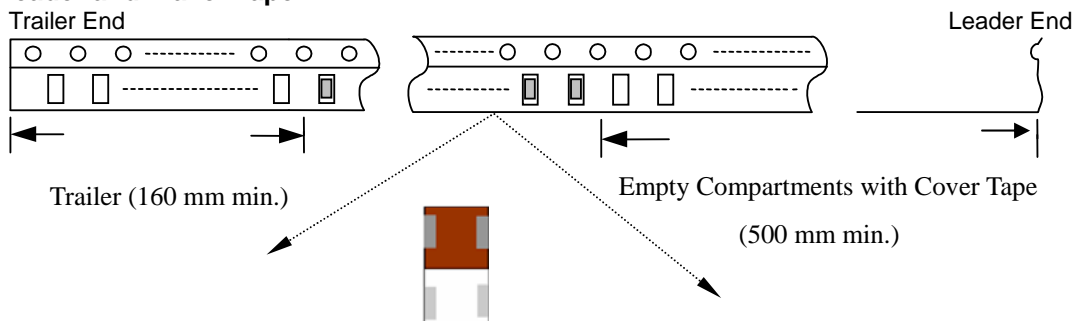
❖Reel Dimensions (Unit: mm)



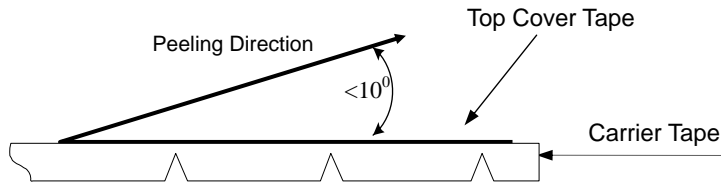
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
1005	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

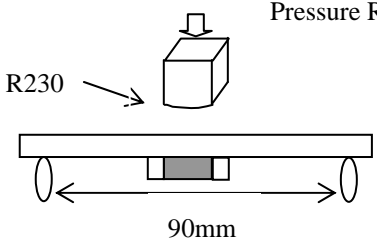
❖ **Storage Conditions**

- (1) Temperature: 5 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

Notes

- ❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

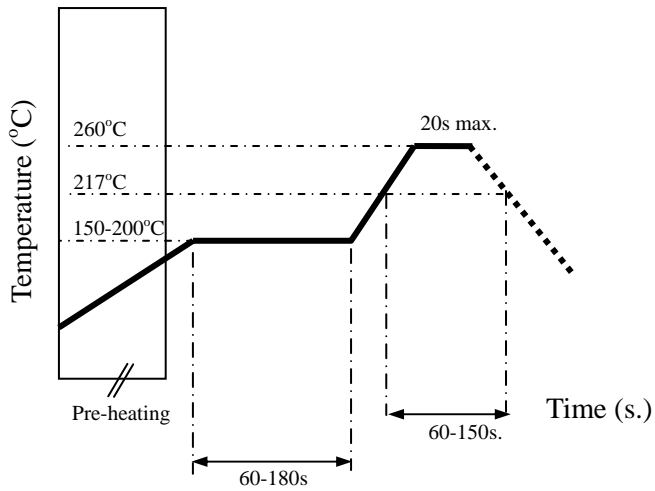
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 95% of the terminal electrode shall be covered with new solder 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $245 \pm 5^\circ\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> 3N minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	<ol style="list-style-type: none"> No apparent damage 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 1.6mm) using the recommend soldering profile. Apply a bending force of 2mm deflection. 
Heat/Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 90% ~ 95% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/step 1 : $125 \pm 5^\circ\text{C}$ for 30 min step 2 : $-40 \pm 5^\circ\text{C}$ for 30 min No of cycles : 100 Recovery: 1-2 hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 500 ± 24hrs Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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